	<spe< td=""><td><u>CIFICAT</u></td><td>ION></td><td></td></spe<>	<u>CIFICAT</u>	ION>	
То :				DIQ-SPE-047(00) 1. 8, 2022
	CUSTOM	ER'S PRODUCT NA	ME	
	ASDI PRO	DUCT NAME:		
	AMPI602	20N-SERIES		
	•			
	DITIONAL CONSENT		CONDITIONAL CC	DNSENT
	APPROVED		CHECKED	
ASDI SIGNATURE				
	APPROVED	CHECKED	PREPARED	
	Xianglong Li	Liang Wang	Jiayin Cai	



Xiamen ASDI Electronics Co.,Ltd.

REV.	DATE	DESCRIPTION	APPROVED	CHECKED	PREPARED
00	Jan. 8, 2022	New release	Xianglong Li	Liang Wang	Jiayin Cai

CAUTION WHEN HANDLING

Before use the products, please read this specification.

CAUTION FOR SAFETY USING

When use the products, be careful to mentioned below for safety using.

	CAUTION	
*The product should be used withi	n 12 monthes.	
Focus on the storage conditions.		
Solderability may become weak if	it exceeds the period.	
*Do not use and store the product		
(Salt,Acid,Alkaline).	5	
*The products must be preheated	before soldering.	
The operating temperature includi		/ithin '- 25 ~ +125℃.
*Rework by soldering iron;Please I	keep the mentioned conditions in	this specification.
*In case of insert P.C. Board on ch	nassis, do not add mechanical str	ess to the product.
*Be careful to arrange of non-mag		·
The error may be caused by magr	netic field coupling.	
*In case handle the products, plea	se use wrist strap for ground stat	ic discharge on human
body.		-
The product keeps away from mag	gnet or magnetized things.	
*Do not use the product beyond th	e mentioned conditions in this sp	ecification.
*About an application		
The products listed on this specific	cation sheet are intended for use	in general electronic
equipment		
(AV equipment, telecommunication		
computer equipment, personal equ		rement equipment,
industrial robots) under a normal o	-	
*The products are not designed or		
listed below, whose performance a		
reliability, or whose failure, malfun		
person or property. Please unders	•	
liability caused by use of the produ		
exceeding the range or conditions	-	
1)Aerospace/Aviation equipment	6)Transportation control equip	
2)Military equipment	7)Power-generation control ed	
3)Seabed equipment	which directly endanger hu	
4)Safety equipment	8)Atomic energy-related equip	
5)Medical equipment	9)Other applications that are r	
If you internal to your the same dynate in	considered general-purpose	
If you intend to use the products in	i the rollowing applications, pleas	e contact our sales
office.	leatric trains, china, ata \ Dublic ::	formation processing
Transportation equipment (cars, el		
equipment, Electric heating appara		a prevention/chme
prevention equipment When using this product in genera	l purposo applications, you are ki	indly requested to take
into consideration securing protect		
ensure higher safety.		j backup circuits, etc., lo
ensure nigher salety.		
	DWG.No.	
en ASDI Electronics Co.,Ltd.	DWG.NO.	ISSUE

CUSTOMER	ASDI PART No.	CUSTOMER'S DWG NO.
Each Corporation	AMPI6020N-SERIES	

1.INDEX

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2.Manufacturing Location

China

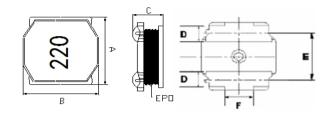
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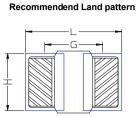
(1)Features

1.This specification applies Low Profile Power Inductors. 2.100% Lead(Pb) & Halogen-Free and RoHS compliant.



(2)Dimensions





C(mm)	D(mm)	E(mm)	F(mm)	L(mm)
2.0 max	1.35±0.2	4.6±0.3	4.0±0.2	6.3

L(mm)	G(mm)	H(mm)
6.3	4.7	5.7

(3)Part Numbering

AMPI	6020	Ν	-	1R0	Ν
А	В	С		D	E

B(mm)

6.0±0.2

Series

AMPI6020N

A: Series B: Dimension

C: Control S/N

A(mm)

6.0±0.2

1R0=1.0µH D: Inductance E: Inductance Tolerance M=±20%; N=±30%

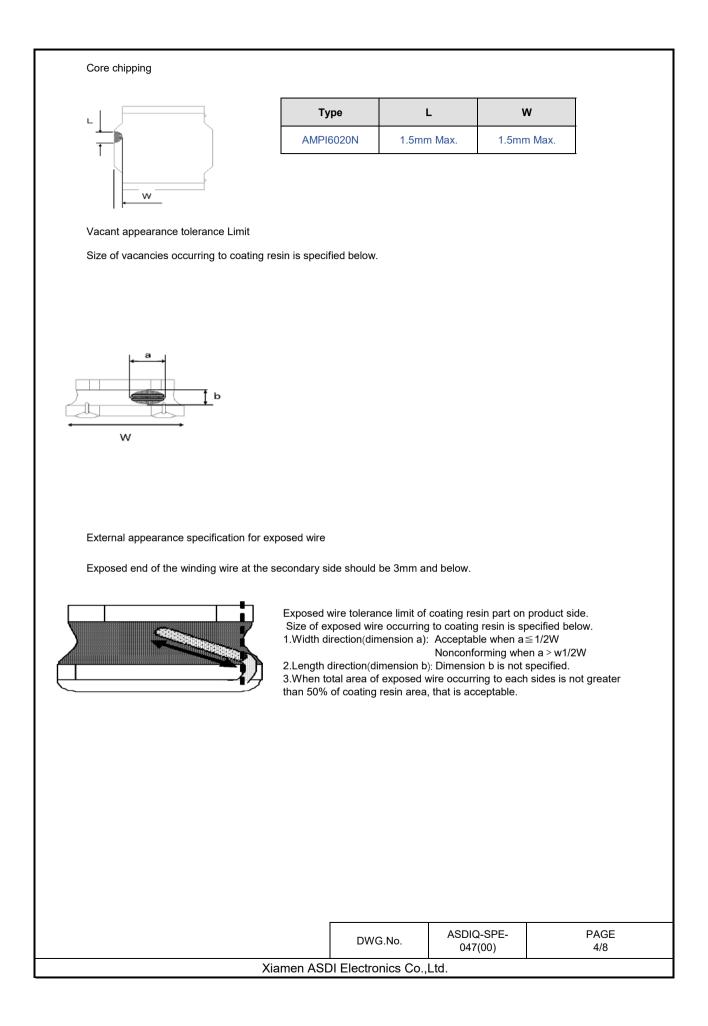
(4)Electrical Specifications Table 1_____

ASDI Part Number	Inductance (µH)	Tolerance (%)	Test Frequency	SRF (MHz) min.	DCR (Ω) ±20%	l sat (A)	I rms (A)
AMPI6020N-1R0N	1.0	±30%	100kHz/1V	110	0.020	5.20	3.80
AMPI6020N-1R5N	1.5	±30%	100kHz/1V	93	0.026	4.30	3.60
AMPI6020N-2R2N	2.2	±30%	100kHz/1V	73	0.034	3.20	2.90
AMPI6020N-3R3N	3.3	±30%	100kHz/1V	55	0.040	2.80	2.75
AMPI6020N-4R7M	4.7	±20%	100kHz/1V	43	0.058	2.40	2.15
AMPI6020N-6R8M	6.8	±20%	100kHz/1V	30	0.085	2.00	1.80
AMPI6020N-100M	10.0	±20%	100kHz/1V	18	0.125	1.90	1.60
AMPI6020N-150M	15.0	±20%	100kHz/1V	16	0.160	1.60	1.30
AMPI6020N-220M	22.0	±20%	100kHz/1V	11	0.290	1.25	0.95
AMPI6020N-330M	33.0	±20%	100kHz/1V	10	0.340	1.00	0.80
AMPI6020N-470M	47.0	±20%	100kHz/1V	9	0.400	0.85	0.72

Notes

lsat: Based on inductance change (\triangle L/L0: \leq -30%) @ ambient temp. 25°C lrms: Based on temperature rise (\triangle T: 40°C typ.)

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(5)Material List

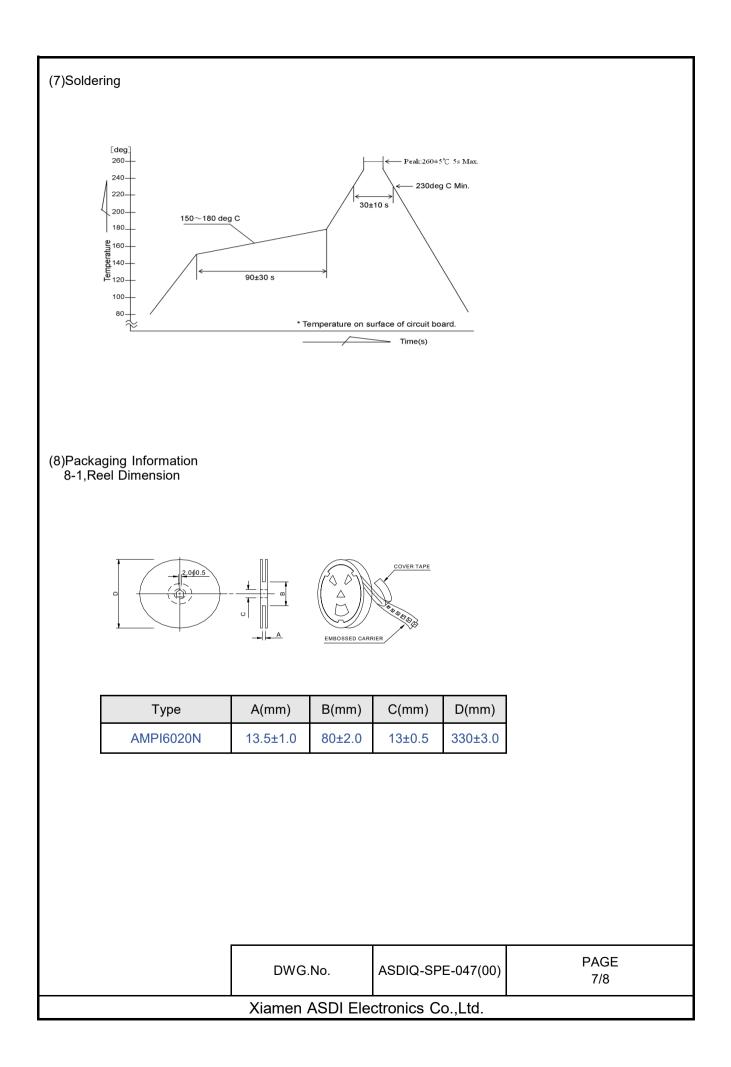
D Ç	3
	-
~	4

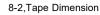
	No.	Items	Materials
	1	Core	Ni-Zn ferrite
	2	Wire	Copper Wire
	3	Coating	Ероху
D	4	Solder	Lead free

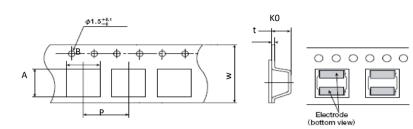
(6)Reliability Tests

No.	Test item	Perform	ance	Test d	etails		
1	Operating temperature	- 25 ~ +1	25 ℃.	Including self-generated he	at		
2	Storage Temperature	-40 ~ +85 °C. - 5 to 40 °C for the product with taping.					
3	Rated current						
4	Inductance (L)	Within the speci	Within the specified tolerance		LCR Meter: HP 4285A or equivalent, 100kHz, 1V		
5	DC Resistance			DC Ohmmeter: HIOKI3227	DC Ohmmeter: HIOKI3227 or equivalent		
6	Temperature characteristics	Inductance change	ə: Within±20%	Measurement of inductance temperature rang within-25 With reference to inductance rate shall be calculated. Measurement of inductance temperature rang within-40 With reference to inductance rate shall be calculated.	°C to +85°C. œ value at+20°C,change e shall be taken at °C to +125°C.		
7	Resistance to flexure substrate	No dan	nage	The test samples shall be s board by the reflow. As illustrated below, apply f arrow indicating until deflect reaches to 2mm. Substrate size: 100x40x1. Substrate material: glass e Solder cream thickness: 0	Force in the direction of the tion of the test board $\begin{array}{c} \hline \\ \hline $		
8	Adhesion of Terminal electrode	Shall not come off PC board.		board and by the reflow. 10 N, 5 Applied force: 10 N to X and Duration: 5s	Applied force: 10 N to X and Y directions.		
9	Resistance to Vibration	Inductance change No abnormality observ		The test samples shall be soldered to the test board by the reflow. Then it shall be submitted to below test conditions. Frequency: 10-55Hz Total Amplitude: 1.5mm (May not exceed acceleratio 196m/S2) Sweeping Method:10Hz to 55Hz to 10Hz for 1min. Time: 2 hours each in X,Y, and Z Direction. Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.			

No.	Test item	Performance	Test details	
10	Solderability	At least 90% of surface of terminal electrode is covered by new solder.	The test samples shall be dipped in flux, and then immersed in molten solder as shown in below. Flux: methanol solution containing rosin 25% Solder temperature: 245±5 °C Time: 5±1.0 sec. Immersion depth: All sides of mounting terminal shall be immersed.	
11	Resistance to soldering	Inductance change:Within±10% No abnormality observed in appearance.	The test sample shall be exposed to reflow oven at 230±5℃ for 40 seconds, with peak temperature at 260±5℃ for 5 seconds,2 times. Test board thickness: 1.0mm Test board material: glass epoxy-resin	
12	Thermal shock		The test samples shall be soldered to the test board by the reflow. The test samples shall be placed at specified temperature for specified time by step 1 to step 4 as shown below in sequence. The temperature cycles shall be repeated 100 cycles . Phase Temperature(C) Time(min.) 1 -40±3C 30±3 2 Room Temp Within 3	
13	Damp heat life test	b T o si T H H No abnormality observed in appearance. T o a b T T o A A A A	Test Method and Remarks The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below. Temperature: 60±2°C Humidity: 90~95%RH Time: 500+24/-0 hrs	
14	Loading under damp heat life test		The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below. Temperature: $60\pm2^{\circ}$ C Humidity: 90-95%RH Applied current: Rated current Time: 500+24/-0 hrs	
15	Low temperature life test		The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below. Temperature:- 40 ± 2 °C Time:500+24/-0 hrs	
16	Loading at high temperature life test		The test samples shall be soldered to the test board by the reflow. Temperature: 85±2℃. Applied current: Rated current Time: 500+24/-0 hrs.	







Series	A(mm)	B(mm)	Ko(mm)	P(mm)	W(mm)	t(mm)
AMPI6020N	6.3±0.1	6.3±0.1	3.1±0.1	8.0±0.1	12.0±0.3	0.4±0.1

8-3, Packaging Quantity

Туре	Chip / Reel		
AMPI6020N	2000		

(9)Note

·Storage Conditions

To maintain the solderability of terminal electrodes:

1. ASDI products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.

2. Temperature and humidity conditions: Temperature: 5 to 30deg.C, Humidity: 75% Max.

3. Recommended products should be used within 12 months form the time of delivery.

4. The packaging material should be kept where no chlorine or sulfur exists in the air.

·Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.

2. The use of tweezers or vacuum pick up is strongly recommended for individual components.

3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

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单击下面可查看定价,库存,交付和生命周期等信息

>>ASDI